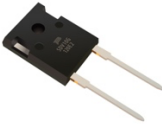


MATERIAL DECLARATION SHEET



Material Number	BSDV10G120E2 TO247-2			
Product Line	Semiconductor			
Compliance Date	2023-5-22			
RoHS Compliant	YES	MSL	N.A.	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Die	Silicon Carbide	2.49	Silicon Carbide (SiC)	409-21-2	100	0.042	0.042
2	Die Attach	Die Attach	0.06	Diethylene Glycol Monoethyl Ether Acetate	112-15-2	5	0.001	0.018
			1.03	Silver (Ag)	7440-22-4	95	0.017	
3	Lead Frame	Copper alloy	1.2	Phosphorous (P)	7723-14-0	0.03	0.02	67.277
			3.99	Iron (Fe)	7439-89-6	0.1	0.067	
			3984.81	Copper (Cu)	7440-50-8	99.87	67.19	
4	Mold Compound	Resin	124.34	Phenol Formaldehyde resin (generic)	9003-35-4	6.5	2.097	32.257
			306.08	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	16	5.161	
			1358.23	Silica fused	60676-86-0	71	22.902	
			124.34	Silica-amorphous	7631-86-9	6.5	2.097	
5	Plating	Tin plating	22	Tin (Sn)	7440-31-5	100	0.371	0.371
6	Wire	Pure metal	2.11	Aluminium (Al)	7429-90-5	100	0.036	0.036
Total weight			5930.68 mg					

This Document was updated on: 2023/5/22

(EU) RoHS Directive 2011/65/EU ANNEX Application of lead which are exempted from the requirements